



## Senior Packaging Design Engineer

### **Are you passionate about new technologies and future-oriented projects in semiconductor design? Photeon is the place for you!**

As a market leader in turnkey solutions, Photeon offers the opportunity to work on a diverse range of products across Automotive, Compute, Industrial, Medical, and other markets. We are seeking a dynamic Senior Packaging Design Engineer to join our team and drive our projects to success. We provide an energetic, exciting, and friendly environment with numerous opportunities for your professional growth in the direction that suits you best.

We welcome you to become a key contributor to our success, fostering collaboration and teamwork every step of the way.

#### **Your Role:**

As a Semiconductor Packaging Design Engineer, you'll be the mastermind behind next-gen chiplet architectures, 3D packaging, and SiP (System-in-Package) technologies. You'll collaborate across cross-functional teams and OSAT partners to deliver highly reliable, thermally optimized, and structurally sound package solutions.

- Develop and optimize packaging architectures for advanced semiconductor devices
- Perform thermal simulations and structural analyses to validate design integrity
- Integrate chiplet and 3D packaging concepts into manufacturable solutions
- Collaborate with OSATs on package design, testing, and quality validation
- Lead failure analysis investigations and propose design improvements
- Ensure design meets performance, reliability, and manufacturability targets
- Communicate technical insights across engineering, product, and operations teams
- Drive innovation and continuous improvement in packaging design methods

#### **Your Profile:**

- Bachelor's or Master's degree in Electronics, Materials Science, or related field
- 5+ years of hands-on experience in semiconductor packaging design
- Strong understanding of electrical and mechanical aspects of packaging
- Proficiency in thermal simulation tools and structural analysis methodologies
- Familiarity with chiplet architectures, SiP, and 3D packaging techniques
- Experience interfacing with OSATs and managing package-level testing
- Clear communicator and a collaborative team player
- Demonstrated problem-solving and analytical skills with a creative edge
- Good verbal and written English skills, German or Italian a plus

#### **What We Offer:**

- Opportunity to work with cutting-edge technology and a talented team.
- Personal development and individual training plans.
- Innovative products and business environment.
- Flexible working hours.
- Friendly and supportive environment.
- Exciting, varied work in a growing and internationally active company.
- Comprehensive onboarding and ongoing support.
- Modern office spaces.
- Team building events.
- Competitive compensation well above the relevant collective agreement.



**Are you ready to shape the future of semiconductor technology aimed at enabling solutions for a better life?** We look forward to receiving your application at [recruiting@photeon.com](mailto:recruiting@photeon.com).

**Location:** Dornbirn, Austria or Pavia, Italy

**Contact**

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